

AUIRL1404L-VB Datasheet N-Channel 40 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}$ (Ω)	I _D (A) ^{a, c}	Q _g (Typ.)			
40	$0.0017 \text{ at V}_{GS} = 10 \text{ V}$	150	120 nC			
	0.0025 at V _{GS} = 4.5 V	135	120110			

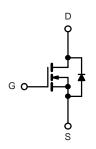
FEATURES

- TrenchFET® Power MOSFET
- 100 % R_g and UIS Tested



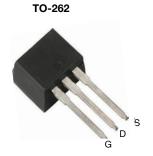
APPLICATIONS

- Synchronous Rectification
- Power Supplies



N-Channel MOSFET

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0.0017 at $V_{GS} = 10 \text{ V}$	150	120 n
0.0025 at $V_{GS} = 4.5 \text{ V}$	135	12011



Top View

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	40	V	
Gate-Source Voltage		V _{GS}	± 25		
	T _C = 25 °C		150 ^{a, c}	A	
Continuous Drain Current /T 475 °C	T _C = 70 °C		120 ^c		
Continuous Drain Current (T _J = 175 °C)	T _A = 25 °C	I _D	29 ^b		
	T _A = 70 °C		23 ^b		
Pulsed Drain Current	I _{DM}	380			
Avalanche Current Pulse		I _{AS}		80	
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	320	m.	
Continuous Courses Brain Binds Coursest	T _C = 25 °C	1	110 ^{a, c}		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	2.6 ^b	A	
	T _C = 25 °C		312 ^a		
Maximum Power Dissipation	T _C = 70 °C	D	200	w	
	T _A = 25 °C	P _D	3.13 ^b		
	T _A = 70 °C		2.0 ^b		
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient ^b Steady State		R _{thJA}	32	40	°C/W		
Maximum Junction-to-Case	Steady State	R _{thJC}	0.33	0.4	C/VV		

Notes:

- a. Based on T_C = 25 °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. Calculated based on maximum junction temperature. Package limitation current is 110 $\,\mathrm{A.}$



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V, } I_D = 250 \mu\text{A}$	45			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	V_{DS}/T_J $I_D = 250 \mu\text{A}$		41		m\//°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	1 _D = 230 μΛ		- 8		mV/°(
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.2		2.5	V	
Gate-Source Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zoro Coto Voltago Drain Current	I _{DSS}	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current		$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α	
David Course Co. Otata Basista and	D	V _{GS} = 10 V, I _D = 30 A		0.0017			
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}$	0.0025			Ω	
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, I_{D} = 30 \text{ A}$		180		S	
Dynamic ^b	•						
Input Capacitance	C _{iss}			9000		pF	
Output Capacitance	C _{oss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		650			
Reverse Transfer Capacitance	C _{rss}			450			
Total Gate Charge	Q_{g}			120	180	nC	
Gate-Source Charge	Q_{gs}	$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$		30			
Gate-Drain Charge	Q _{gd}			16			
Gate Resistance	R_{g}	f = 1 MHz		0.85	1.3	Ω	
Turn-On Delay Time	t _{d(on)}			20	30		
Rise Time	t _r	V_{DD} = 20 V, R_L = 1.0 Ω		11	17	-	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 20 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		77	115		
Fall Time	t _f			10	15		
Turn-On Delay Time	t _{d(on)}			102	155	ns	
Rise Time	t _r	V_{DD} = 20 V, R_L = 1.0 Ω		62	95		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 20 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		180	270		
Fall Time	t _f			60	90		
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			110	^	
Pulse Diode Forward Current ^a	I _{SM}				200	Α	
Body Diode Voltage	V _{SD}	I _S = 20 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			50	75	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	L = 20 A di/dt = 100 A/v = T = 05 °C		70	105	nC	
Reverse Recovery Fall Time	ta	$I_F = 20 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		30			
Reverse Recovery Rise Time	t _b			20		ns	

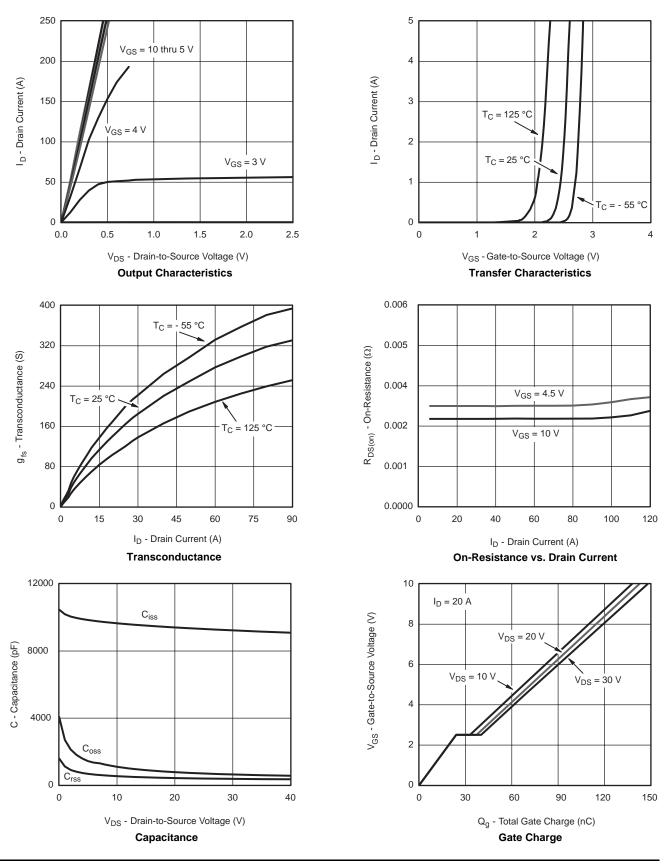
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

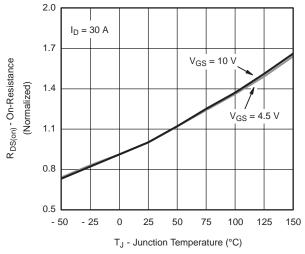


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

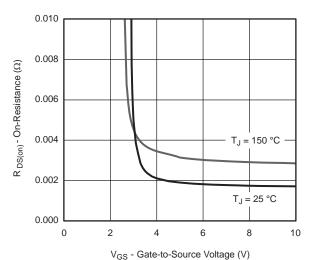




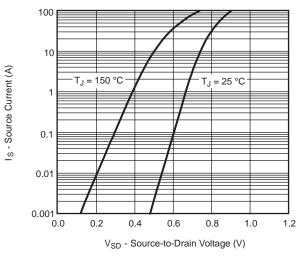
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On-Resistance vs. Junction Temperature



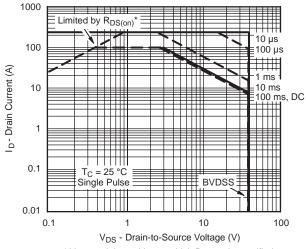
On-Resistance vs. Gate-to-Source Voltage



Forward Diode Voltage vs. Temperature



Threshold Voltage

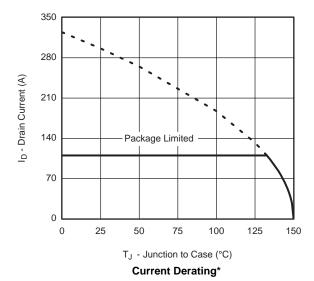


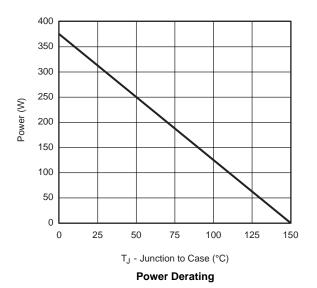
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





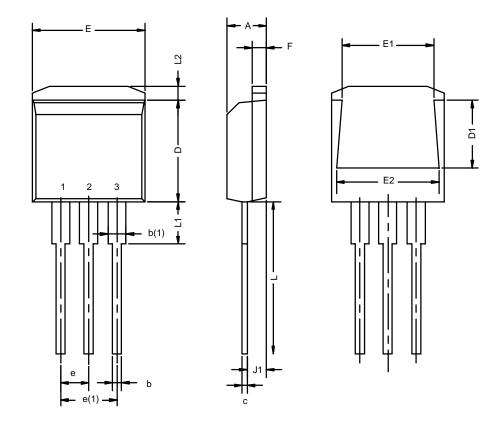
* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



Normalized Thermal Transient Impedance, Junction-to-Case



TO-262: 3-LEAD



	MILLIMETERS* INCHES			HES
Dim	Min	Max	Min	Max
Α	4.32	4.70	0.170	0.185
b	0.64	1.00	0.025	0.039
b(1)	1.14	1.40	0.045	0.055
С	0.36	0.50	0.014	0.020
D	8.64	9.65	0.340	0.380
D1	5.59	6.10	0.220	0.240
е	2.41	2.67	0.095	0.105
e(1)	4.95	5.33	0.195	0.210
Е	10.03	10.41	0.395	0.410
E1	7.87	8.64	0.310	0.340
E2	9.02	9.53	0.355	0.375
F	1.14	1.40	0.045	0.055
J1	2.41	2.79	0.095	0.110
L	13.08	14.22	0.515	0.560
L1	-	3.81	-	0.150
L2	1.02	1.40	0.040	0.055
ECN: T-022 DWG: 585	234—Rev. C, 1 5	4-Oct-02		

^{*}Use millimeters as the primary measurement



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